Specification

Drawing No.	TNY1T-H1-SEN01-00 [1/7]
Issued Date.	1-Oct-18

TO: Digikey

Note: In case of specification change, KYOCERA Part Number also will be changed.

Product Name	Crystal Oscillator
Product Model	
Frequency	64 MHz
Customer Part Number	
Customer Specification Number	
KYOCERA Part Number	KC2016K64.0000C3GN00
Remarks RoHS Compliant	/ MSL 1

Customer Acceptance

Accept Signature	Accept Date	
	Department	
	Person in charge	

KYOCERA Corporation

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Design Department	Quality	Approved by	Checked by	legued hy
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Crystal Components Division				

Drawing No. TNY1T-H1-SEN01-00 [2/7]

Revision History

Rev. No.	Description of revise	Date	Approved by	Checked by	Issued by
00	First Edition	1-Oct-18			

TNY1T-H1-SEN01-00 [3/7]

1. Scope

This specification shall be defined of the Clock Oscillator for the integrated circuits (ICs).

2. Customer Part Number

3. KYOCERA Part Number

KC2016K64.0000C3GN00

4. Electrical Characteristics

4-1. Absolute Maximum Rating

ltem	Symbol	Rated Value	Units
Power Supply Voltage	V _{CC}	-0.3 to +7.0	V
Input Voltage	V_{IN}	-0.3 to V _{CC} +0.3	٧
Storage Temperature	T_{STG}	-55 to +125	°C

Note

If the part is used beyond absolute maximum ratings, it may cause internal destruction. The part should be used under the recommended operating conditions the reliability of this part may be damaged if those conditions are exceeded.

4-2. Recommended Operating Conditions

ltem	Symbol	Min	Тур	Max	Units	Remarks
Power Supply Voltage	V_{CC}	2.97	3.3	3.63	V	
Input Voltage	V_{IN}	0		V _{CC}	V	
Operating Temperature	T_{OPR}	-40	25	+85	°C	

4-3. Electrical Characteristics

Item	Symbol	Min	Тур	Max	Units	Remarks
Output Frequency	Fo		64		MHz	
Frequency Tolerance*	F_tol	-50		+50	ppm	
Current Consumption	I_{CC}			18	mA	
Standby Current	I _{ST}			10	μΑ	
Symmetry (Duty Ratio)	SYM	45	50	55	%	@50% Vcc
Rise Time/ Fall Time (10% V _{CC} to 90% V _{CC})	Tr/ Tf			5	ns	
Output Voltage-"L"	V_{OL}			10% V _{CC}	V	IoL= 8mA
Output Voltage-"H"	V_{OH}	90% V _{CC}			V	Iон= -8mA
Output Load	CL			15	pF	CMOS
Input Voltage-"L"	V_{IL}			30% V _{CC}	V	
Input Voltage-"H"	V_{IH}	70% V _{CC}			V	
Output Disable Time	t_ _{dis}			150	ns	
Output Enable Time	t_ena			5	ms	
Start-up Time	t_ _{sta}			5	ms	@Minimum operating voltage to be 0sec
1 Sigma Jitter**	J_{Sigma}			4	ps	
Peak to Peak Jitter**	J_{PK-PK}			40	ps	
Phase Jitter				0.5	ps	BW:12kHz to 20MHz
			-92			@10Hz offset
			-126			@100Hz offset
Phase Noise			-151			@1kHz offset
@25MHz Typical			-160		dBc/Hz	@10kHz offset
			-167			@100kHz offset
			-170			@1MHz offset
			-170			@10MHz offset

Note: All electrical characteristics have defined on the maximum loaded and recommended operating conditions.

^{*} Include initial tolerance, operating temperature range, rated power supply voltage change, load change, aging (1year @+25°C), shock and vibration

^{**}Based on Time Interval Analyzer "Wavecrest SIA-3000".

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4-4. Measurement Condition

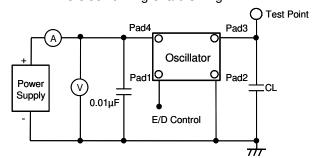
The reference temperature shall be $+25\pm2^{\circ}$ C. The measurement shall be performed at the temperature range of $+5^{\circ}$ C to $+35^{\circ}$ C unless otherwise the result is doubtful.

4-5. Measurement Circuit

The electrical characteristics shall be measured by test circuit "Fig. 1". Also jitter shall be measured by test circuit "Fig. 3".

4-6. Clock Timing Chart

The clock timing chart is "Fig. 2".



Note: CL includes probe and test fixture capacitance

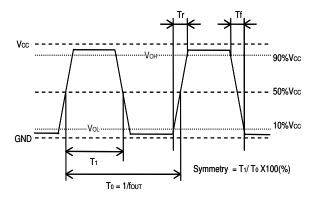
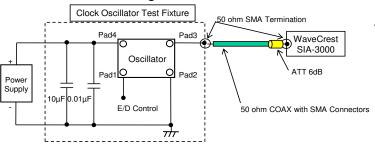


Fig.2 Clock Timing Chart (C-MOS Output)

Fig.1 Test Circuits

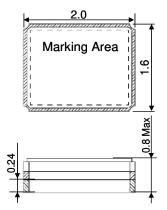


<Measurement Conditions>

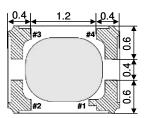
- Time Interval Analyzer
 - ➤ WaveCrest SIA-3000
- DTS timer calibration
 - Over 30 minutes warm-up
 - > Extend 30 minutes calibration
 - Jitter histogram conditions (Tail-fit)
 - More than 50,000cyc Hits
 - ➤ Bit Error Ratio (BER) –12 (14sigma)

Fig.3 Jitter Test Circuits

5. Dimensions and Marking



Pad arrangement						
1 Enable/Disable						
2	Case GND					
3	Output					
4	V _{CC}					



Plating Ni+Au Tolerance:+/-0.2 Unit:(mm)

Enable/Disable Function						
Pad1	Pad3 (Output)					
OPEN	Active					
"H" Level	Active					
"L" Level	High Z (No-Oscillation)					



Output Frequency

The output frequency is three-digit without a decimal point. The frequency greater than the number of digits have rounded down.

(E.g. 14.31818MHz → "14N3")

Manufacturing Date Code

Year	Code	Year	Code	П	Month	Code	П	Day	Code	Day	Code	Day	Code
2001	Α	2011	L	Н	1	1		1	1	11	В	21	M
2002	В	2012	M	Н	2	2		2	2	12	С	22	z
2003	С	2013	N	Н	3	3		3	3	13	D	23	P
2004	D	2014	P	Н	4	4		4	4	14	E	24	σ
2005	E	2015	Q	Н	5	5		5	5	15	F	25	R
2006	F	2016	R	Н	6	6		6	6	16	G	26	s
2007	G	2017	S	Н	7	7		7	7	17	Н	27	Т
2008	Н	2018	T	Н	8	8		8	8	18	J	28	V
2009	J	2019	V	Н	9	9		9	9	19	K	29	V
2010	K	2020	W	Н	10	Α		10	Α	20	L	30	X
lt repea	It repeats from A in 2021 and			Н	11	В						31	Υ
afterw a	ards.			Ш	12	С							

e.g. :"P4A" means "Apr-10-2014"

Table 2

6. Parts Numbering Guide

KC2016K 64.0000 C 3 G N В

A. Series (SMD Oscillator)

B. Output Frequency

C. Output

C: C-MOS

D. Supply Voltage

3: 3.3V

E. Frequency Tolerance*

G: ±50ppm

F: Symmetry (Duty Ratio) and Enable/Disable Function

N: Symmetry: 45% to 55% with Stand-by Function G. Suffix for Individual Requirements

(STD Specification is "00")

Packing (Tape & Reel 2,000pcs/Reel)

*Over All Conditions:

Include initial tolerance, operating temperature range, rated power supply voltage change, load change, aging (1year @+25°C), shock and vibration

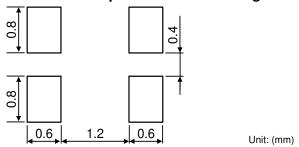
7. Environmental Characteristics

	Items	Conditions	Criteria of Acceptance	
7-1.	Solderability	Soaking:	Dipped potion:	
		+245±5°C, 5.0±0.5sec	Minimum 95% coverage	
7-2.	Soldering Heat	Reflow soldering:	Without looseness or crack etc	
	Resistance	Peak +260°C max, 10sec, Twice max	Williout looselless of clack etc	
7-3.	Temperature Cycle	10cycles:		
		-55°C to +125°C (30minuts each/ cycle)		
7-4.	Mechanical	5 times		
	Shock (Pulse)	14,750m/sec ² (1,500G), Duration of pulse 0.5msec		
		(MIL-STD-883D-2002.3 Condition B)		
	Vibration	4 times each axis X, Y, Z:		
7-5		20 to 2,000Hz and 2,000Hz to 20Hz/cycle	Clause 7-10 shall be satisfied.	
, 5.		Peak acceleration 196m/sec ² (20G)		
		(MIL-STD-883D-2007.2 Condition A)		
7-6.	High Temperature	1000 hours:		
		Temperature: +85+5/-3°C		
7-7.	Low Temperature	1000 hours:		
		Temperature: -40+5/-3°C		
	Humidity Cycle	10 cycles:		
7-8.		Based on 1004 specifications	Clause 7-1 shall be satisfied.	
		(MIL-STD-883D-1004.7)		
7-9.	Hermeticity 1	Soaking:	No bubbles appeared	
	(Gross leak)	+125°C, 5minutes	 	
7-10	.Hermeticity 2	Measured by Helium Detector Equipment	5x10 ⁻⁹ Pa m ³ /sec max	
	(Fine leak)	(MIL-STD-883D-1014.10 Condition A1)	SXIU Fa III /SeC IIIaX	

After each testing, the parts shall be subjected to standard atmospheric conditions more than 2 hours. After that, the electrical characteristics shall be measured. The result of the test shall be satisfied Table 1.

Table 3

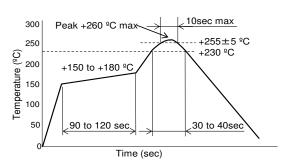
8. Recommended Land pattern and Soldering Guide



Note:

Since the part doesn't have Bypass Capacitor between $V_{\rm cc}$ and GND, Please mount high frequency type capacitor $0.01\mu F$ to the nearest position of oscillator.

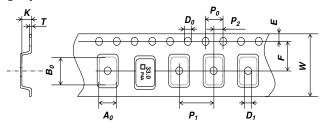
Fig.4 Land pattern



Available Reflow times: Maximum twice

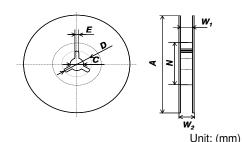
Fig.5 Reflow profile (Lead Free Available)

9. Taping Specifications



					Unit: (mm)
Symbol	\boldsymbol{A}_{0}	\boldsymbol{B}_{o}	W	F	Ε
Dimensions	1.8±0.1	2.25±0.1	8.0±0.2	3.5±0.05	1.75±0.1
Symbol	P 1	P_2	P_{o}	D_{o}	T
Dimensions	4.0±0.1	2.0±0.05	4.0±0.1	1.5+0.1/-0	0.2±0.05
Symbol	K	D ₁			
Dimensions	0.9±0.1	1.1±0.1			

9±0.1 1.1±0.1 Fig.6 Emboss Carrier Tape



			Ornic (min)
Symbol	Α	N	W ₁
Dimensions	180 +0/-1.5	60+1/-0	9.0+0.3/-0
Symbol	W_2	С	D
Dimensions	11.4±1.0	13.0±0.2	21.0±0.8
Symbol	E		
Dimensions	2.0±0.5		

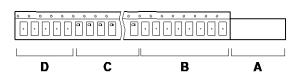
Fig.7 Reel

9-1. Taping Quantities

- The taping of per reel shall be packed 2,000 pcs.
- The parts shall be contained continuously in the pocket.

9-2. Leader and Blank Pockets

- The package shall be consisted of leader, blank pockets and loaded pocket as follows "Fig. 8".
- The power of peeling strength between top tape and carrier tape shall be 0.1N(10gf) to 0.7N(70gf) as follows "Fig. 9".



- A) Leader
- B) Blank Pocket (40mm to 320mm) A+B: 400mm to 560mm
- C) Load Pocket
- D) Blank Pocket (160mm minimum)

Fig.8 Packing Method

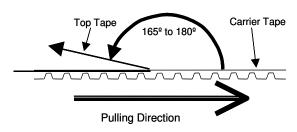


Fig.9 Peeling Strength

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9-3. Reel Label

The reel label shall be consisted as below. (Based on EIAJ C-3 format)

A) Customer Part Number

D) Shipping Date

B) Lot No.

E) Vender Name

C) Quantities

9-4. Exterior Package Label

The oscillator shall be packed properly to avoid defect in transportation. The exterior package label shall be consisted as below.

A) Name of Customer

E) Quantities

B) P/O No.

F) Shipping Date

C) Customer Part Number

G) Vender Name

D) Lot No.

10. The agreement of this specifications

In case there is any obscure point or doubt concerning the contents of the specification, it shall be settled through consultation of both parties.

11. Remarks on Usages

A) Storage Conditions

The parts shall be stored in temperature range of -5 to +40 °C, humidity 40 to 60% RH, and avoid direct sunlight. Then the parts shall be used within 6 months.

B) Handling Conditions

Although the part has protection circuit against static electricity, when excess static electricity is applied, the inside IC may get damaged.

Before mounting on the PCB, please make sure the direction of the part is correct. Otherwise the part of temperature will increase. And also the part will have some damages.

Please do not use the parts under the unfavorable condition such as beyond specified range in this specification.

Please do not use the parts under the condition, in the water or in the salt water also environment of dew or harmful gas.

Please make sure the condition of pick and place following pick up nozzle guideline.

Picking Method: Case of Head Unit 1.6 x 1.2mm (Inside Diameter)

The proper condition of pick and place will be different each equipment. Therefore, please check before testing.

C) Rework Condition

Please do not pick up Head Unit. We can't guaranty electrical performance and reliability.

D) Soldering Conditions

This product can respond to the general Pb-free reflow profile. The wave soldering cannot be supported.

E) Soldering in Mounting

In case of Solder paste and conductive glue contact product lid or product side face exception for product terminal it's possible to influence product characteristics.

Please be careful above contents.

F) Washing Conditions

Ultra sonic cleaning is available. However there is a possibility that Crystal in the part may cause damaged under certain condition. Therefore please test before using.

After washing, please dry the parts completely. Otherwise water drops between the parts and PCB may cause migration.

In case of using this part without above precaution, Kyocera is unable to guarantee the specific characteristics.